



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3BR4765J		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001714666						
<b>Package</b>		PG-DIP-8-15		<b>Weight*</b>		550.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.480	0.45	0.45	4503	4503
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		97	
	non noble metal	zinc	7440-66-6	0.213	0.04		387	
	non noble metal	iron	7439-89-6	4.266	0.77		7747	
wire	non noble metal	copper	7440-50-8	173.237	31.46	32.28	314578	322809
	noble metal	gold	7440-57-5	0.423	0.08	0.08	767	767
encapsulation	organic material	carbon black	1333-86-4	1.801	0.33		3271	
	plastics	epoxy resin	-	48.629	8.83		88304	
	inorganic material	silicondioxide	60676-86-0	309.782	56.24	65.40	562527	654102
leadfinish	non noble metal	tin	7440-31-5	7.496	1.36	1.36	13612	13612
plating	noble metal	silver	7440-22-4	0.801	0.15	0.15	1454	1454
glue	plastics	epoxy resin	-	0.265	0.05		482	
	noble metal	silver	7440-22-4	1.250	0.23	0.28	2271	2753
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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